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(54) **Title:** CARRYING DEVICE, PROCESS CHAMBER AND SEMICONDUCTOR PROCESS APPARATUS

(54) 发明名称: 承载装置、工艺腔室及半导体工艺设备

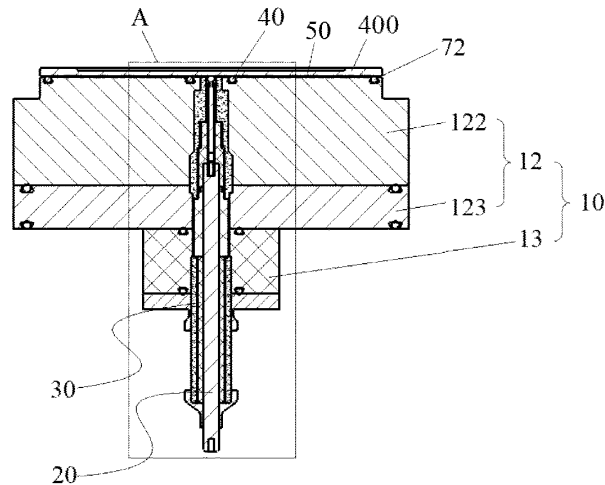


图 2

(57) **Abstract:** Provided in the present application are a carrying device, a process chamber and a semiconductor process apparatus. The carrying device comprises: a support assembly, the top thereof being provided with a carrying surface, and the support assembly being further provided with an introduction channel, the introduction channel extending from the bottom of the support assembly to the carrying surface; a conductive assembly which passes through the inside of the introduction channel, the conductive assembly being configured to electrically connect to an electrostatic tray, thus feeding an external voltage into a suction electrode in the electrostatic tray; and a sealing assembly which is sleeved outside of the conductive assembly and is sealingly connected to the conductive assembly, the sealing assembly being connected to the bottom of the support assembly and being in sealing fit with the support assembly, thus sealing off the end of the introduction channel that is located at the bottom of the support assembly. The solution of the present application solves the problem in the sealing of a process chamber when an electrostatic tray separates from a carrying device or a sealing ring

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MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UY, UZ, VC, VN, WS, ZA, ZM, ZW。

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本国际公布:
— 包括国际检索报告(条约第21条(3))。

ages, improving wafer quality.

(57) 摘要: 本申请提供一种承载装置、工艺腔室及半导体工艺设备。承载装置包括: 支撑组件, 顶部具有承载面, 支撑组件还具有引入通道, 引入通道自支撑组件的底部延伸至承载面; 导电组件, 穿设在引入通道内, 导电组件用于与静电托盘电连接, 以将外部电压馈入静电托盘内的吸附电极上; 密封组件, 套设在导电组件的外部, 且与导电组件密封连接, 密封组件连接在支撑组件的底部并与支撑组件密封配合, 以将引入通道位于支撑组件底部的一端封闭。本申请的方案解决了在静电托盘与承载装置分离或密封圈老化时工艺腔室出现密封问题, 提高了晶圆的质量。